TOSHIBA CMOS Digital Integrated Circuit Silicon Monolithic

T6L08

Gate Driver for TFT LCD Panels

The T6L08 is a 240-channel-output gate driver for TFT LCD $\,$ panels. In addition to high-voltage operation (liquid crystal drive voltage = max 42 V), this device accepts external input of the panel drive voltage, allowing you to change the low-level output voltage. Thus, this device can be used for various TFT LCD panel drive systems.

The T6L08 offers high integration circuit due to CMOS technology.

Features

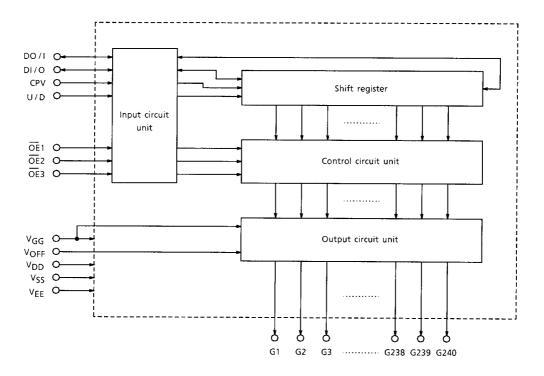
- LCD drive output pins : 240 pins
- LCD drive voltage
- : Max VEE + 42 V
- Data transfer method
 - : Bidirectional shift register : −20 to 75°C Operating temperature
- Package
- : Tape carrier package (TCP)

		Unit: mm	
T6L08	User Area Pitch		
	IN	OUT	
(SAN, 3NS)	0.9	0.1	
(SBN, 4DS)	0.9	0.1	

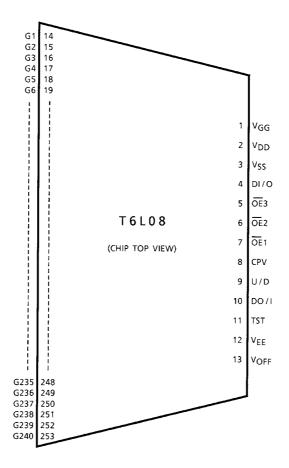
Please contact Toshiba or a distributor for the latest TCP specification and product line-up.

TCP (Tape Carrier Package)

Block Diagram



Pin Assignment



The above diagram shows the device's pin configuration only and does not necessarily correspond to the pad layout on the chip. Please contact Toshiba or our distributors for the latest TCP specification.

Pin Function

Pin Name	I/O			Function				
		Vertical shift data I/O pins. These pins are used to input and output shift data. These pins are switched between input and output by setting the U/D pin as shown below.						
			U/D	DI/O	DO/I			
DI/O	I/O		Н	Input	Output			
DO/I	1/0		L	Output	Input			
		latched into the When set for outp When two or m	I to feed data into the shift registers at the r ut ore T6L08s are casca	shift registers at the firs ising edge of CPV. ded, this pin outputs the th the falling edge of CF	e data to be fed into the			
U/D	Input	This pin specific When U / D is $G1 \rightarrow G2 \rightarrow$ When U / D is $G240 \rightarrow G23$	Transfer direction select pin This pin specifies the direction in which data is transferred through the shift registers. When U / D is high, data is shifted in the direction $G1 \rightarrow G2 \rightarrow G3 \rightarrow G4 \rightarrow G5 \rightarrow \cdots \rightarrow G240$ When U / D is low, the direction is reversed to give $G240 \rightarrow G239 \rightarrow G238 \rightarrow G237 \rightarrow \cdots \rightarrow G1$ The voltage applied to this pin must be a DC-level voltage that is either high (V _{DD}) or low (V _{SS}).					
CPV	Input	Vertical shift clock This is the shift clock for the shift registers. Data is shifted through the shift registers synchronously with the rising edge of CPV.						
\overline{OE} 1 to \overline{OE} 3	Input	These signals of The V _{OFF} vo	Output enable input These signals control the data appearing at the LCD panel drive pins (G1 to G240). The V _{OFF} voltage is output when \overrightarrow{OE} 1 to \overrightarrow{OE} 3 are high; normal shift data is output when \overrightarrow{OE} 1 to \overrightarrow{OE} 3 are low.					
VOFF	Input	corresponding	Analog input pin If the shift register data is low (= logic 0), the voltage on this pin is forwarded to the output pin corresponding to the shift register. If \overrightarrow{OE} 1 to \overrightarrow{OE} 3 are high, the voltage on this pin is output irrespective of whether the shift register data is high or low.					
TST	Input	Test pin Leave this pin o	open.					
G1 to G240	Output	These pins out	LCD panel drive pins These pins output the shift register data, or the voltage applied to V _{GG} or V _{OFF} , depending on the control signals \overline{OE} 1 to \overline{OE} 3.					
V _{GG}		Power supply for	LCD drive					
V _{DD}	_	Power supply for	the internal logic					
V _{SS}	_	Power supply for	the internal logic					
V _{EE}	—	Power supply for	LCD drive and the inte	ernal logic				

Device Operation (See Timing Diagram)

(1) Shift data transfer method

The input shift data is latched into the internal register synchronously with the rising edge of the shift clock CPV. When the data is shifted to the next register at the next rising edge of CPV, new input shift data is simultaneously latched into.

In the case of shift data output, the data in the last shift register is output synchronously with the falling edge of CPV (the output high voltage level is V_{DD} ; the output low voltage level is V_{SS}).

U/D	DI/O	DO/I	Data Transfer Method
Н	Input	Output	$DI/\:O\toG1\toG2\toG3\to\cdots\cdots\toG240\toDO/I$
L	Output	Input	$DO/I \to G240 \to G239 \to G238 \to \cdots \cdots \to G1 \to DI/O$

(2) LCD panel drive outputs

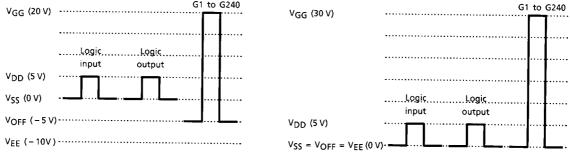
If the shift register data corresponding to an output pin is high (= logic 1), the pin outputs V_{GG} ; if the shift register data is low (= logic 0), the pin outputs V_{OFF} .

However, if \overline{OE} 1 to \overline{OE} 3 corresponding to the output pins are high, the pins output V_{OFF} irrespective of whether the shift register data is high or low. The LCD panel drive outputs are controlled by \overline{OE} as shown below.

Output Ena	ıble Pin	Lcd Panel Drive Outputs				
H/L	OE 1 to 3	LCD Panel Drive Pins Controlled By OE	Output			
	OE 1	G1, G4, G7, G10 ······ G235, G238				
L	OE 2	G2, G5, G8, G11 ······ G236, G239	Normal data output			
	OE 3	G3, G6, G9, G12 ······ G237, G240				
OE 1		G1, G4, G7, G10 ······ G235, G238				
Н	OE 2	G2, G5, G8, G11 ······ G236, G239	V _{OFF}			
	OE 3	G3, G6, G9, G12 ······ G237, G240				

(3) Voltage setting

(Exa	mple 1) N	legative voltage output	
•	L	ogic input	: High = 5 V or low = 0 V amplitude
	S	upply voltage	: V _{GG} = 20 V
			$V_{DD} = 5 V$
			$V_{OFF} = -5 V$
			$V_{EE} = -10 V$
	L	CD panel drive output	: High level = V _{GG} (20 V)
			Low level = V_{GG} (-5 V)
(Exa	mple 2) P	ositive voltage output	
	L	ogic input	: High = 5 V or low = 0 V amplitude
	S	upply voltage	: V _{GG} = 30 V
			$V_{DD} = 5 V$
			$V_{OFF} = V_{SS} = V_{EE} = 0 V$
	L	CD panel drive output	: High level = V _{GG} (30 V)
			Low level = V _{OFF} (0 V)
(*) Lo	gic input p	pins	: DI/O or DO/I, CPV, \overline{OE} 1 to \overline{OE} 3, U/D
		C	1 to G240
VGG	(20 V)		V _{GG} (30 V)

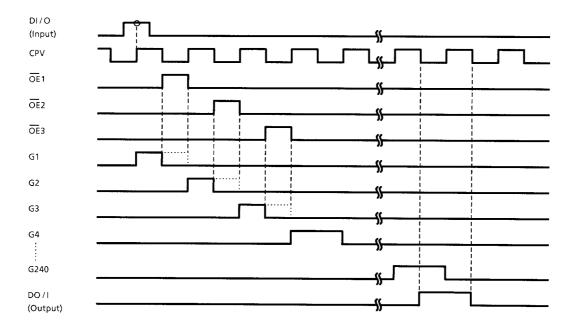


(Example 1)

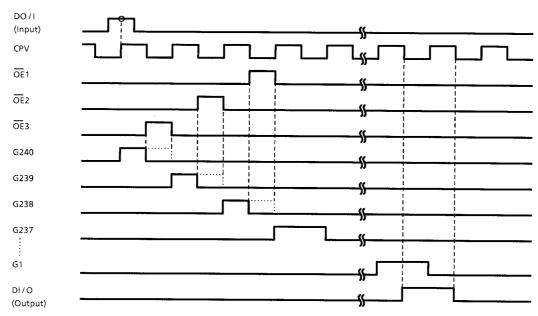
(Example 2)

Timing Diagrams

• UP mode (U/D = high)



• DOWN mode (U/D = low)



Absolute Maximum Ratings ($V_{SS} = 0 V$)

Parameter	Symbol	Rating	Unit
Supply Voltage (1)	$V_{GG} - V_{EE}$	15.0 to 45.0	V
Supply Voltage (2)	V _{DD}	-0.3 to 7.0	V
Supply Voltage (3)	V _{EE}	-16.0 to 0.3	V
Input Voltage	V _{IN}	-0.3 to V _{DD} + 0.3	V
Analog Input Voltage	V _{OFF}	$V_{\mbox{\scriptsize EE}}$ – 0.3 to $V_{\mbox{\scriptsize GG}}$ + 0.3	V
Storage Temperature	T _{STG}	–55 to 125	°C

Recommended Operating Conditions (V_{SS} = 0 V)

Parameter	Symbol	Rating	Unit
Supply Voltage (1)	$V_{GG} - V_{EE}$	15.0 to 42.0	V
Supply Voltage (2)	V _{DD}	4.5 to 5.5	V
Supply Voltage (3)	V _{EE}	-15.0 to 0	V
Operating Temperature	T _{op} –20 to 75		°C
Operating Frequency	F _{CPV}	DC to 100	kHz
Output Load Capacitance	C _L 300 (max)		pF / pin
Analog Input Voltage	V _{OFF} (Note 1)	-15.0 to 0	V

Note 1: $V_{EE} \leq V_{OFF}$

Electrical Characteristics

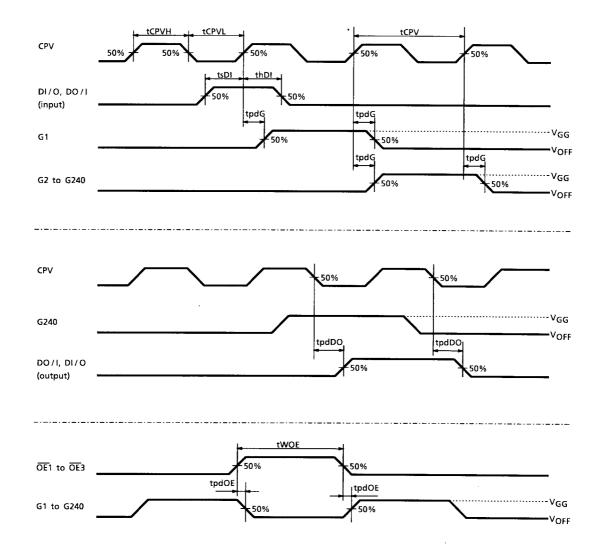
DC Characteristics (V_{GG} – V_{EE} = 42 V, Ta = –20 to 75°C)

Parameter		Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit	Relevant Pin	
Input	Low Level	VIL			V _{SS}	_	$\begin{array}{c} 0.2 \times \\ (V_{DD} - V_{SS}) \\ + V_{SS} \end{array}$	V	(Note 2)	
Voltage	High Level	V _{IH}			$\begin{array}{c} 0.8 \times \\ (V_{DD} - V_{SS}) \\ + V_{SS} \end{array}$		V _{DD}	v	(11018 2)	
Output	Low Level	V _{OL}		I _{OL} = 40 μA	V _{SS}		V_{SS} + 0.3 V	V	DI/O,	
Voltage	High Level	V _{OH}		I _{OH} = -40 μA	V_{DD} – 0.3 V	_	V _{DD}	v	DO/I	
Output Low Level		R _{OL}		V_{OUT} = V_{OFF} + 0.5 V	—	_	1500	Ω	G1 to G240	
Resistance	High Level	R _{OH}		V_{OUT} = V_{GG} – 0.5 V	—	_	1500	12	GT 10 G240	
Input Leakage Current		I _{IN}	_	_	-1.0	_	_	μA	(Note 2)	
Current Consumption (1)		I _{GG}	_	_	—	_	_	μA	V _{GG}	
Current Consumption (2)		I _{DD}	_		—	—		μA	V _{DD}	
Current Consumption (3)		I _{SS}			-200	_		μA	V _{SS}	

Note 2: Input pins include ... DI/O, DO/I, U/D, CPV, $\overline{OE} 1$ to $\overline{OE} 3$

AC Characteristics (V_{GG} – V_{EE} = 42 V, Ta = –20 to 75°C)

Parameter	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Clock Period	tCPV	—	_	10			μS
CPV Pulse Width (H)	tCPVH	_	_	4	_	_	μS
CPV Pulse Width (L)	tCPVL	—	_	4			μS
OE Enable Time	twOE	—	_	1			μS
Data Set-up Time	tsDI	_		1			μS
Data Hold Time	thDI	—	_	1			μS
Output Delay Time (1)	tpdDO	—	C _L = 50 pF	_		1	μS
Output Delay Time (2)	tpdG	—	C _L = 300 pF			1	μS
Output Delay Time (3)	tpdOE		C _L = 300 pF	_	_	1	μS



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